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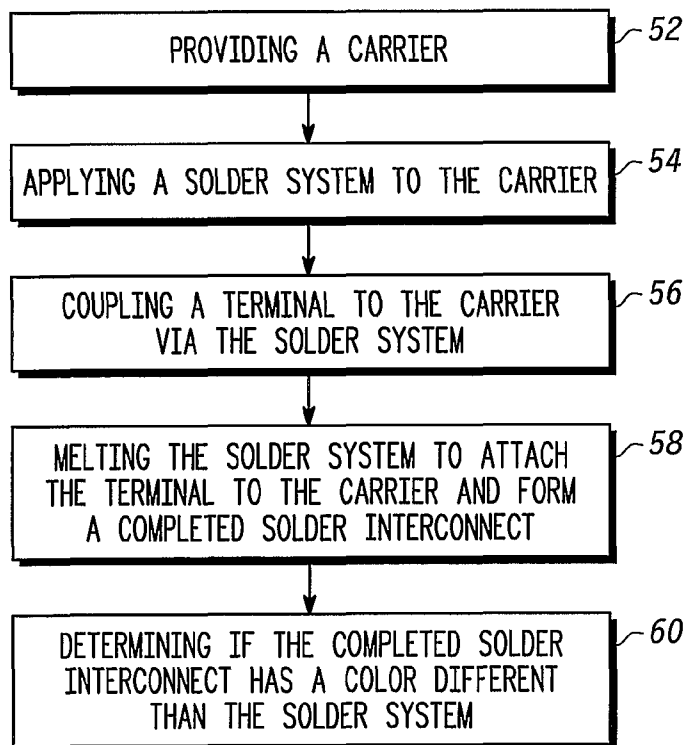
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(54) Title: LEAD SOLDER INDICATOR AND METHOD



(57) Abstract: A solder system (14) includes a lead (Pb) indicator and a solder flux. A method for forming a semiconductor device includes providing a carrier (52), applying the solder system to the carrier (54), coupling the terminal to the carrier via the solder system (56), melting the solder system to attach the terminal to the carrier and form a completed semiconductor device (58), and determining if the completed semiconductor device has a different predetermined property from the solder system (60).



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